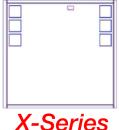
## **MMIC**

## REFLECTIONLESS FILTER DICE

 $50\Omega$  DC to 21 GHz

## The Big Deal

- Patented design eliminates in band spurs
- Pass band cut-off up to 21 GHz
- Stop band up to 35 GHz
- Excellent repeatability through IPD\* process
- Unpackaged Die Form



Available in Low Pass, High Pass and Band Pass designs

## **Product Overview**

Mini-Circuits' X-Series reflectionless filters employ a novel filter topology which absorbs and terminates stop band signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stop band, sending signals back to the source at 100% of the power level which interact with neighboring components and often result in intermodulation and other interferences. Reflectionless filters eliminate stop band reflections, allowing them to be paired with sensitive devices and used in applications that otherwise require circuits such as isolators, isolation amplifiers or attenuators.

Key Features	Advantages
Easy integration with sensitive reflective components, e.g. mixers, multipliers	Reflectionless filters absorb unwanted signals, preventing reflections back to the source. This reduces generation of additional unwanted signals without the need for extra components like attenuators, improving system dynamic range and saving board space.
Enables stable integration of wideband amplifiers	Because reflectionless filters maintain good impedance in the stop band; they can be integrated with high gain, wideband amplifiers without the risk of creating instabilities in these out of band regions.
Cascadable	Reflectionless filters can be cascaded in multiple sections to provide sharper and higher attenuation, while also preventing any standing waves that could affect pass band signals.
Excellent power handling in a tiny surface mount device	High power handling extends the usability of these filters to the transmit path for inter-stage filtering.
Excellent repeatability of RF performance	Through semiconductor IPD process, X-series filters are inherently repeatable for large volume production.
Excellent stability over temperature	With ±0.3 dB variation over temperature ideal for use in wide temperature range applications without the need for additional temperature compensation.
Operating Temperature up to 105°C	Suitable for operation close to high power components
Unpackaged Die form	Enables direct integration into customer hybrids

<sup>\*</sup>IPD - Integrated Passive Device, is a GaAs semiconductor process



# Reflectionless High Pass Filter Die

XHF-1832-D+

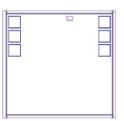
50Ω 18.3 to 40 GHz

#### **Features**

- Match to  $50\Omega$  in the stop band, eliminates undesired reflections
- Cascadable
- Excellent Power handling
- Protected by US Patent No. 8,392,495

## **Applications**

- Wi-Fi
- WiMax
- Microwave Radio
- Military & Space



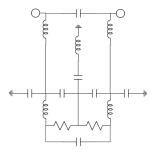
+RoHS Compliant
The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Ordering Information: Refer to Last Page

## **General Description**

Mini-Circuits' XHF-1832-D+ reflectionless filter die employs a novel filter topology which absorbs and terminates stop band signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stop band, sending signals back to the source at 100% of the power level. These reflections interact with neighboring components and often result in inter-modulation and other interferences. Reflectionless filters eliminate stop band reflections, allowing them to be paired with sensitive devices and used in applications that otherwise require circuits such as isolation amplifiers or attenuators.

## **Simplified Schematic**



Pad	Description	
RF-IN	RF Input Pad	
RF-OUT	RF Output Pad	
Ground	Ground Bonding Pad	

Note: 1. Bond Pad material - Gold 2. Bottom of Die - Gold plated



## Electrical Specifications<sup>1</sup> at 25°C

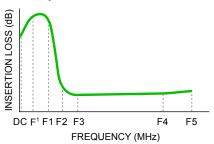
Pa	rameter	F#	Frequency (MHz)	Min.	Тур.	Max.	Unit
	Rejection	DC - F <sup>1</sup>	DC - 9000	_	17.6	_	dB
	Rejection	F1 - F1	9000 - 14600	_	18.3	_	UD
Stop Band	Frequency Cut-off	F2	17400	_	3.0	_	dB
	VSWR	DC - F <sup>1</sup>	DC - 9000	_	1.8	_	:1
	VOVIII	F¹ - F1	9000 - 14600	_	1.3	_	.,
		F3 - F4	18300 - 32000	_	2.1	_	ID.
B B	Insertion Loss	F4 - F5	32000 - 40000	_	1.6	_	dB
Pass Band	VSWR	F3 - F4	18300 - 32000	_	1.6	_	:1
	VOVVII	F4 - F5	32000 - 40000	_	2.0	_	:1

<sup>&</sup>lt;sup>1</sup> Electrical Specifications are typical measured characteristics of die.

## **Absolute Maximum Ratings<sup>4</sup>**

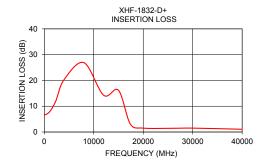
Parameter	Ratings
Operating Temperature	-55°C to +105°C
RF Power Input, Passband (F3-F5) <sup>2</sup>	0.32 W at 25°C
RF Power Input, Stopband (DC-F3)3	0.09 W at 25°C

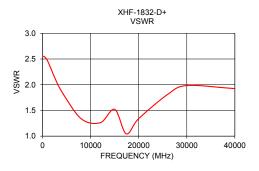
## Specification Definition



## Typical Performance Data at 25°C

Frequency (MHz)	Insertion Loss (dB)	VSWR (:1)
10	6.66	2.55
50	6.66	2.55
100	6.67	2.55
500	6.93	2.53
1000	7.70	2.47
1500	8.97	2.36
2000	10.69	2.25
2400	12.34	2.16
4000	20.31	1.86
8000	26.91	1.34
12000	14.27	1.26
15000	16.18	1.52
17400	3.08	1.05
20000	1.51	1.34
26000	1.45	1.81
30000	1.51	1.98
40000	1.07	1.92







Passband rating derates linearly to 0.16W at 105°C ambient
 Stopband rating derates linearly to 0.04W at 105°C ambient
 Permanent damage may occur if any of these limits are exceeded.

## **Characterization Test Circuit**

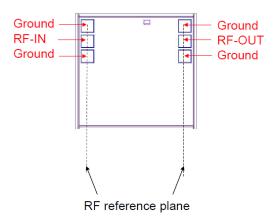


Figure 1: Block Diagram of Test Circuit used for characterization of S-parameters

## Conditions:

1. Input Power= -25dBm

## **Die Layout**

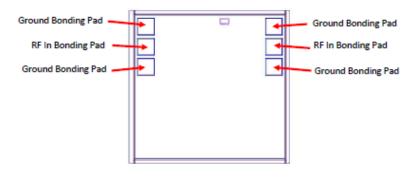
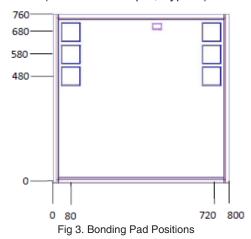


Fig 2. Die Layout

## **Bonding Pad Position**

(Dimensions in µm, Typical)



## **Critical Dimensions**

Parameter	Values
Die Thickness, μm	100
Die Width, µm	800
Die Length, μm	760
Bond Pad Size (Ground pad), µm	75 x 75

## **Assembly and Handling Procedure**

#### 1. Storage

Dice should be stored in a dry nitrogen purged desiccators or equivalent.

#### 2. ESD

MMIC Gallium Arsenide (GaAs) filter dice are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be opened in clean room conditions at an appropriately grounded anti-static worksta tion. Devices need careful handling using correctly designed collets, vacuum pickup tips or sharp antistatic tweezers to deter ESD damage to dice.

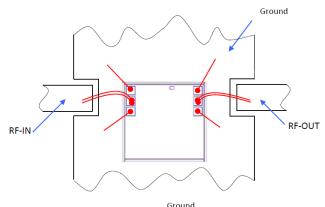
#### 3. Die Attach

The die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are DieMat DM6030Hk-PT/H579/H579 or Ablestik 84-1LMISR4. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy coverage around total die periphery. Parts shall be cured in a nitrogen filled atmosphere per manufac turer's cure condition. It is recommended to use antistatic die pick up tools only.

#### 4. Wire Bonding

Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the dice gold bond pads. Thermosonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1 mil diameter. Bonds must be made from the bond pads on the die to the package or substrate. All bond wires should be kept as short as low as reasonable to minimize performance degradation due to undesirable series inductance.

## **Assembly Diagram**

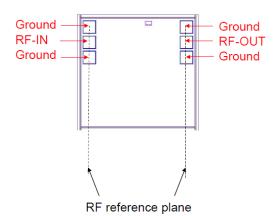


Note: Ground bond wires are optional.

## **Recommended Wire Length, Typical**

Wire	Wire Length (mm)	Wire Loop Height (mm)
All wires	1.0	0.15

## **RF Reference Plane**





Additional Detailed Technical Information additional information is available on our dash board.				
	Data Table			
Performance Data	Swept Graphs			
	S-Parameter (S2P Files) Data Set with and without port extension(.zip file)			
Case Style	Die			
	Quantity, Package	Model No.		
	Small, Gel - Pak: 10,50,100 KGD* Medium <sup>†</sup> , Partial wafer: KGD*<1980	XHF-1832-DG+ XHF-1832-DP+		
Die Ordering and packaging information	Large <sup>†</sup> , Full wafer	XHF-1832-DF+		
	†Available upon request contact sales representative			
	Refer to AN-60-067			
Environmental Ratings	ENV-80			

<sup>\*</sup>Known Good Dice ("KGD") means that the dice are taken from PCM good wafer and visually inspected according to Mini-Circuits inspection criteria. While this is not definitive, it does help to provide a higher degree of confidence that dice are capable of meeting typical RF electrical parameters specified by Mini-Circuits.

## **ESD Rating\*\***

Human Body Model (HBM): Class 1A (250V) in accordance with ANSI/ESD STM 5.1 - 2001

#### **Additional Notes**

- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.
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<sup>\*\*</sup> Tested in industry standard MCLP 3x3mm 12 lead package.

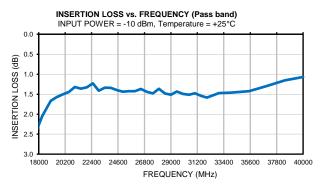
Typical Performance Data

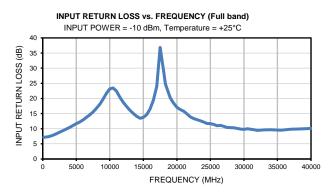
FREQ.	Insertion Loss	Group Delay	Input Return Loss	Output Return Loss
(MHz)	(dB)	(nsec)	(dB)	(dB)
10	6.66	0.86	7.18	7.10
50	6.67	0.85	7.18	7.10
100	6.68	0.75	7.18	7.10
200	6.71	0.75	7.19	7.11
400	6.84	0.73	7.23	7.15
600	7.05	0.71	7.29	7.21
800	7.34	0.77	7.37	7.30
1000	7.70	0.74	7.47	7.41
1500	8.98	0.64	7.85	7.80
2000	10.70	0.51	8.29	8.30
2500	12.81	0.33	8.82	8.84
3000	15.26	0.08	9.34	9.43
3500	17.92	-0.24	9.89	10.03
4000	20.32	-0.57	10.43	10.59
4500	21.78	-0.72	11.07	11.22
5000	21.96	-0.56	11.68	11.85
5500	21.60	-0.28	12.19	12.48
6000	21.37	-0.05	12.92	13.17
6500	21.54	0.08	13.72	13.99
7000	22.33	0.14	14.61	14.81
7500	23.91	0.10	15.53	15.75
8000	26.88	-0.27	16.75	16.87
8500	32.73	-0.27 -2.45	18.07	18.07
9000	32.73 35.22	-2.45 -2.95	19.84	19.58
9500	35.22 26.79	-2.95 -1.12	21.75	21.09
10000	22.01	0.12	23.13	21.90
10500	18.85	0.33	23.47	21.89
11000	16.69	0.40	22.45	21.02
11500	15.21	0.42	20.45	19.56
12000	14.27	0.42	18.76	18.12
12500	13.91	0.39	17.37	16.85
13000	14.08	0.29	16.10	15.67
13500	15.01	0.09	15.05	14.66
14000	16.78	-0.57	14.10	13.72
14500	18.76	-1.38	13.47	13.06
14600	18.70	-1.43	13.50	13.12
15000	16.21	-1.15	13.73	12.97
15500	11.49	-0.14	14.64	13.78
16000	7.91	0.44	16.49	15.46
16500	5.52	0.62	19.46	18.54
17000	3.93	0.64	24.02	23.98
17500	2.82	0.59	36.85	31.87
18000	2.27	0.53	29.38	27.48
18300	2.05	0.49	24.79	23.57
19000	1.67	0.39	20.22	20.12
19500	1.57	0.32	18.44	18.86
20000	1.51	0.31	17.06	16.92
20500	1.45	0.28	16.31	15.53
21000	1.32	0.24	15.79	14.89
21500	1.36	0.24	14.90	14.46
22000	1.33	0.25	13.91	13.95
22500	1.23	0.23	13.35	13.37
23000	1.41	0.21	13.03	12.67
23500	1.34	0.20	12.64	12.38
24000	1.34	0.17	12.19	12.39
24500	1.40	0.16	11.76	12.15
25000	1.44	0.15	11.66	11.59
25500	1.43	0.13	11.42	11.11
26000	1.43	0.12	10.99	11.01
26500	1.37	0.14	11.12	11.00
27000	1.44	0.13	10.76	10.97
27500	1.44	0.12	10.76	10.56
	1.48	0.14	10.43	
28000				10.19
28500	1.48	0.12	10.29	10.11
29000	1.51	0.12	10.10	10.21
29500	1.43	0.09	9.88	10.06
30000	1.49	0.11	9.80	9.87
30500	1.52	0.10	9.99	9.85
31000	1.48	0.09	9.81	9.96
31500	1.54	0.08	9.67	9.73
32000	1.59	0.08	9.46	9.69
33000	1.47	0.10	9.64	9.84
34000	1.46	0.10	9.69	9.88
35500	1.43	0.09	9.54	10.00
37000	1.29	0.10	9.85	9.88
38500	1.15	0.10	9.95	10.27

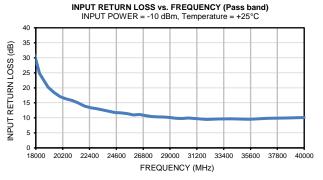


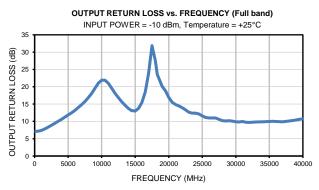
## Typical Performance Curves

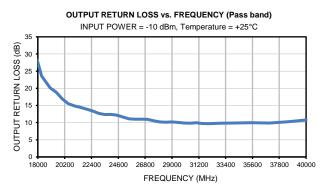


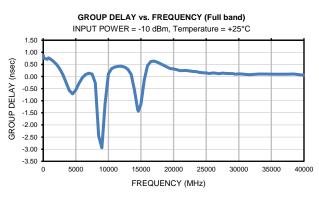


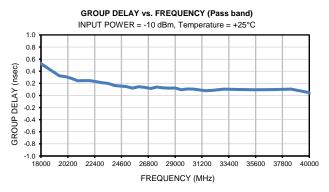


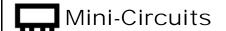












## **Environmental Specifications**

ENV80

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-40° to 85° C or -40° to 105° C or -55° to 105° C Ambient Environment	Refer to Individual Model Data Sheet
Storage Environment	20° to 35° C and 40 to 60% humidity (In Factory Shipped Package)	Individual Model Data Sheet

ENV80 Rev: B 04/16/19 M173783 File: ENV80.pdf